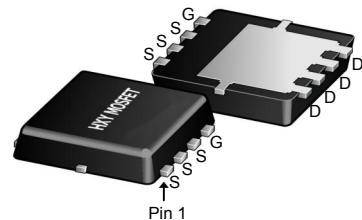




## Description

The BSC067N06LS3G uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = 60V$   $I_D = 80A$

$R_{DS(ON)} < 7m\Omega$  @  $V_{GS}=10V$

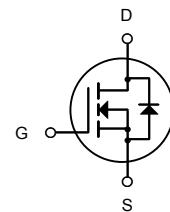
DFN5X6-8L

## Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
BSC067N06LS3G	DFN5X6-8L	80N06 XXX YYYY	5000

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	80	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	52	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	320	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	169	mJ
$P_D@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	108	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.4	°C/W



## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10\text{V}$ , $I_D = 30\text{A}$	-	5.3	7	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	4136	-	pF
$C_{oss}$	Output Capacitance		-	286	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	257	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30\text{V}$ , $I_D=30\text{A}$ , $V_{GS}=10\text{V}$	-	90	-	nC
$Q_{gs}$	Gate-Source Charge		-	9	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	18	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$ , $I_D=30\text{A}$ , $R_G=1.8\Omega$ , $V_{GS}=10\text{V}$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	7	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	40	-	ns
$t_f$	Turn-off Fall Time		-	15	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	80	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	320	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=30\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=30\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	33	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	46	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

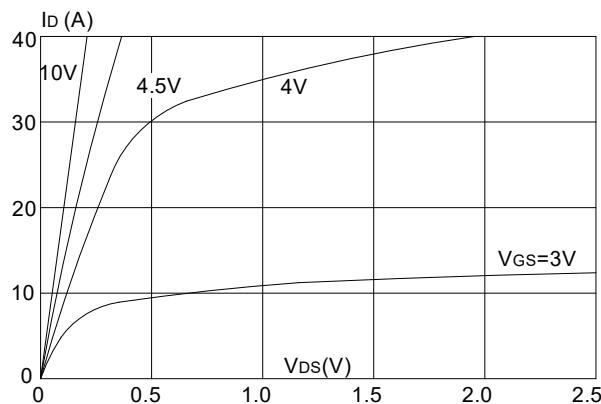
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=26\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

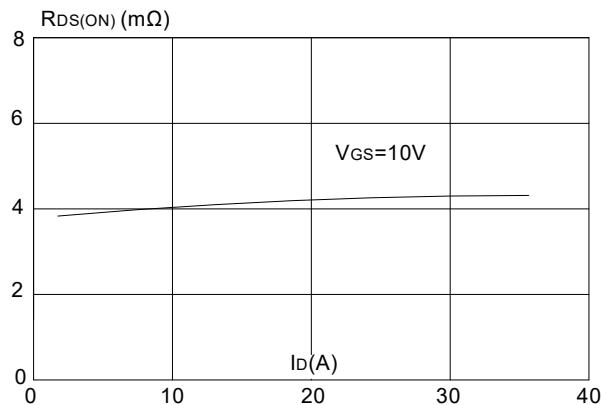


## Typical Performance Characteristics

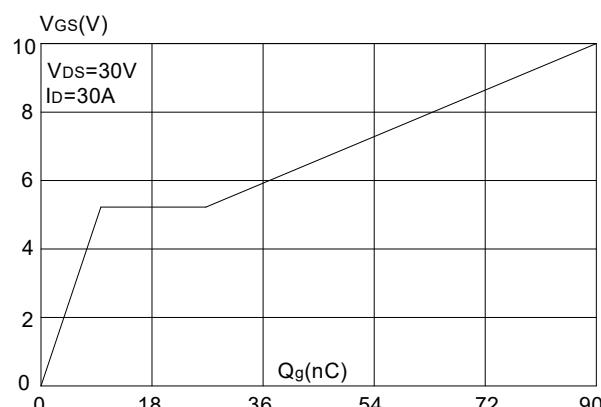
**Figure 1:** Output Characteristics



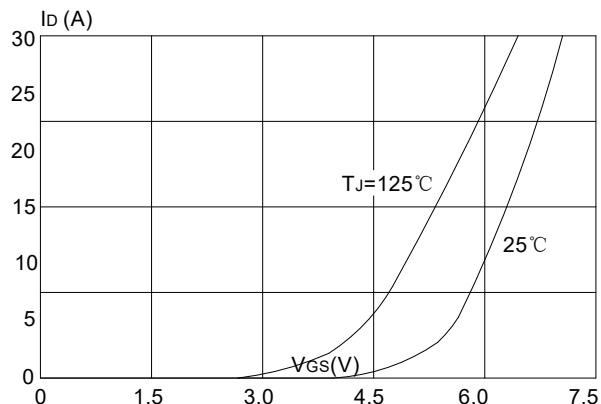
**Figure 3:** On-resistance vs. Drain Current



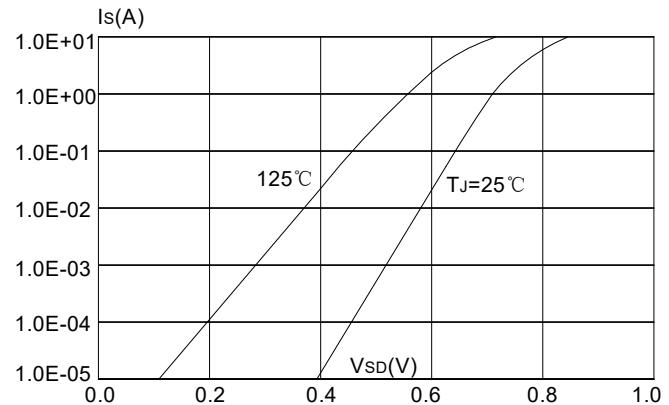
**Figure 5:** Gate Charge Characteristics



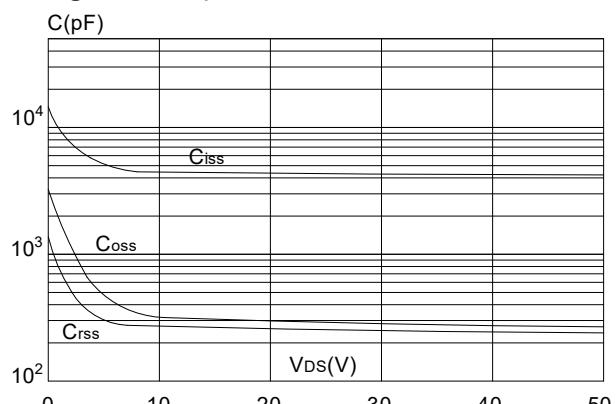
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics

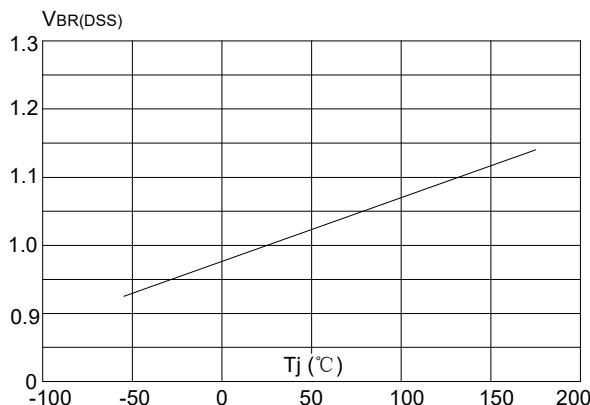


**Figure 6:** Capacitance Characteristics

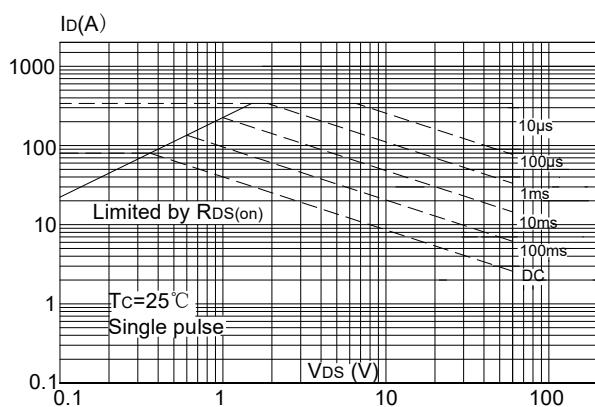




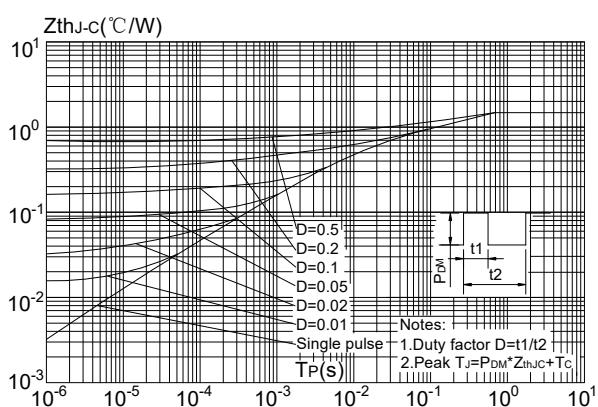
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



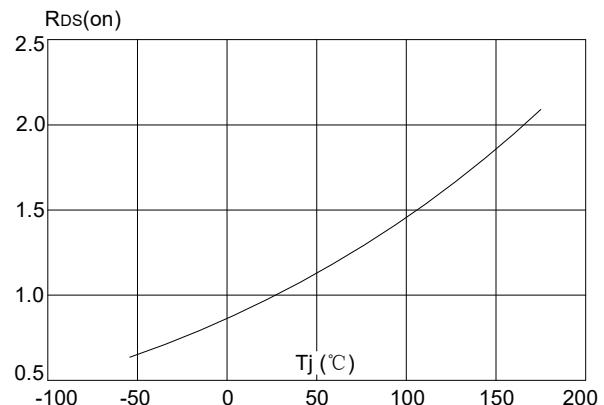
**Figure 9:** Maximum Safe Operating Area



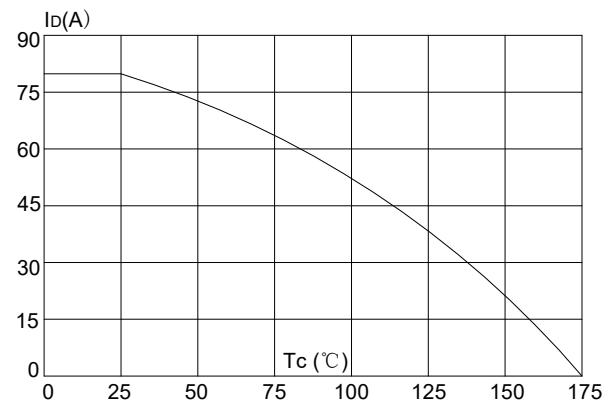
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature

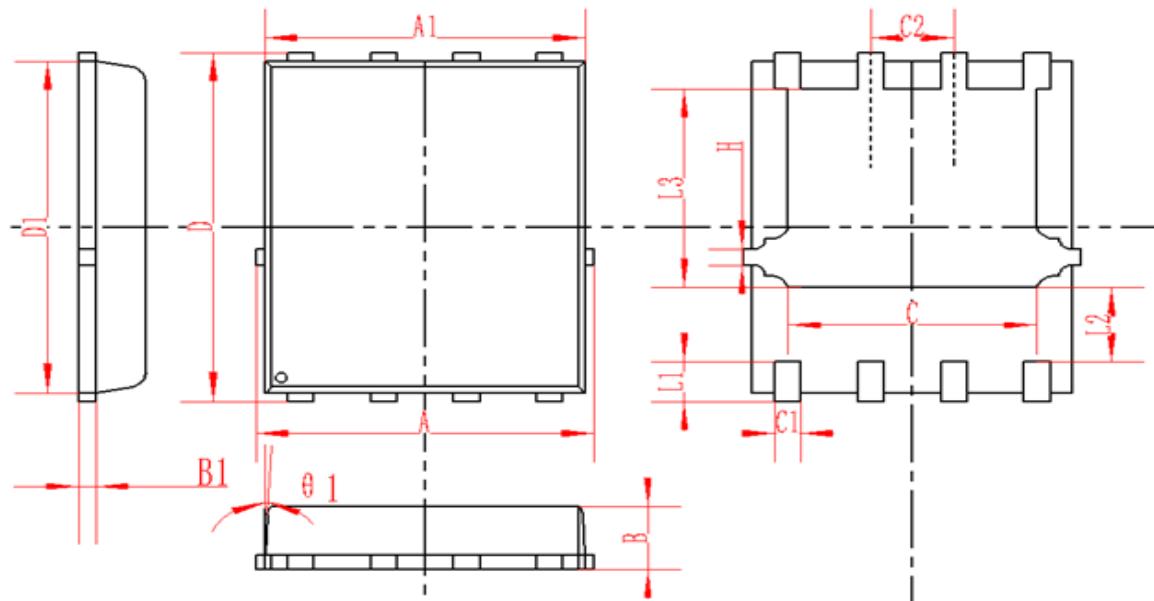


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature





### DFN5X6-8L Package Information



SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
B	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF			0.010REF		
C	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
H	0.24	0.25	0.26	0.009	0.010	0.010



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